

# Matt Tin SAT 10

Matt Tin SAT 10 is a sulphuric acid based electrolyte giving fine crystalline deposits. Special features of the bath are exceptional covering power and excellent solderability. The main application is the tin-plating of electronic or precision components.

Its use as a metal resist deposit in printed circuit manufacture has limited application. Based on our experiences tin electrolytes based on sulphuric acid are sensitive towards impurities caused by photo resist bleeding. The compatibility of Matt Tin SAT 10 with the photo resists to be used must be checked prior to use.

Matt Tin SAT 10 is used in the same composition for barrel or rack applications. The deposits are very solderable even after heat or steam ageing for 16 h/155 °C.

The formation of Sn(IV)compounds is slowed down and therefore clouding of the electrolyte is prevented.

Operating the Matt Tin SAT 10 is simple and easy. It only requires maintenance of the Sn(II) and sulphuric acid contents as well as periodical replenishment of the additives that are mainly consumed by drag-out.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

**The additives required for bath make-up and operation meet the requirements of the RoHS Directive (Restriction of certain Hazardous Substances) relating to the limit of lead, mercury, cadmium, chrome(VI), Polybrominated Biphenyls and Polybrominated Diphenyl Ethers.**

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**Important:**

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at [www.schloetter.com/downloads](http://www.schloetter.com/downloads).

For the storage of chemical products the TRGS 510 must be followed.

**If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.**

